PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Chun-Yuan Wu	04/08/2011
Chih-Chien Liu	04/08/2011
Chin-Fu Lin	04/08/2011
Po-Chun Chen	04/08/2011

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13087379

CH $40.00 13087379

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	JANINE CHANG

Total Attachments: 2
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Docket No NAUP1245USA

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar ($1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):

Name: Chun-Yuan Wu Nationality: TW

Name: Chih-Chien Liu Nationality: TW

Name: Chin-Fu Lin Nationality: TW

Name: Po-Chun Chen Nationality: TW

Hereby sells, assigns and transfers to

ASSIGNEE(S):

Name: UNITED MICROELECTRONICS CORP.

Address: No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"Method of Forming Opening on Semiconductor Substrate"

Which is found in :

(a) + U.S. patent application executed on even date

(b) ____ U.S. patent application executed on ____

(c) ____ U.S. application serial no. ____

(d) ____ patent no. ____ issued ____

(e) ____ International application no. ____

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this APR 0 8 2011 (Date of signing).（請發明人務必簽署上列日期。）

(Type name of inventor)	**Signature of INVENTOR**
Chun-Yuan Wu	Chun-Yuan Wu
Chih-Chien Liu	Chih-Chien Liu
Chin-Fu Lin	Chin-fu Lin
Po-Chun Chen	Po-Chun Chen